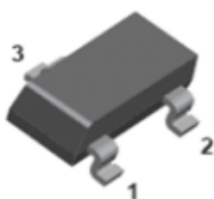
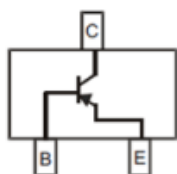


PNP General Purpose Amplifier



SOT-23

Features

- Moisture sensitivity level 1
- Halogen free and RoHS compliant
- Surface mount package ideally suited for automatic insertion
- Epoxy meets UL-94 V-0 flammability rating

Application

- Signal amplification
- Switching circuit

Mechanical data

- **Package:** SOT-23
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102

■ Maximum Ratings ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Device marking code				593
Collector-base voltage	V_{CB0}	V	$I_C=-100\mu\text{A}, I_E=0$	-120
Collector-emitter voltage	V_{CE0}	V	$I_C=-10\text{mA}, I_B=0$	-100
Emitter-base voltage	V_{EB0}	V	$I_E=-100\mu\text{A}, I_C=0$	-5
Collector current	I_C	A		-1
Power dissipation	P_D	mW		250
Junction temperature	T_J	$^{\circ}\text{C}$		-55 to +150
Storage temperature	T_{STG}	$^{\circ}\text{C}$		-55 to +150



FMMT593

RoHS
COMPLIANT

■ Electrical Characteristics (T_a=25°C Unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	Typ	Max
Collector-base breakdown voltage	V _{(BR)CBO}	V	I _C =-100μA, I _E =0	-120		
Collector-emitter breakdown voltage	V _{(BR)CEO}	V	I _C =-10mA, I _B =0	-100		
Emitter-base breakdown voltage	V _{(BR)EBO}	V	I _E =-100μA, I _C =0	-5		
Collector-base cut-off current	I _{CBO}	μA	V _{CB} =-100V			-0.1
Emitter-base cut-off current	I _{EBO}	μA	V _{EB} =-4V			-0.1
DC current gain	h _{FE1}		V _{CE} =-5V, I _C =-1mA	100		
	h _{FE2}		V _{CE} =-5V, I _C =-250mA	100		
	h _{FE3}		V _{CE} =-5V, I _C =-0.5A	100		300
	h _{FE4}		V _{CE} =-5V, I _C =-1A	50		
Collector-emitter saturation voltage	V _{CE(sat)}	V	I _C =-250mA, I _B =-25mA			-0.2
		V	I _C =-500mA, I _B =-50mA			-0.3
Base-emitter saturation voltage	V _{BE(sat)}	V	I _C =-500mA, I _B =-50mA			-1.1
Base-emitter voltage	V _{BE}	V	V _{CE} =-5V, I _C =-1A			-1
Transition frequency	f _T	MHz	V _{CE} =-10V, I _C =-50mA, f=100MHz	150		
Collector-base output capacitance	C _{ob}	pF	V _{CB} =-10V, I _E =0A, f=1MHz		15	

■ Thermal Characteristics

Parameter	Symbol	Unit	Value
Thermal resistance, junction-to-ambient	R _{θJ-A} ⁽¹⁾	°C/W	500
Thermal resistance, junction-to-case	R _{θJ-C} ⁽¹⁾	°C/W	400

Note:

(1) Device mounted on PCB, single-sided copper, with standard footprint

■ Characteristics

Fig 1: Static Characteristics

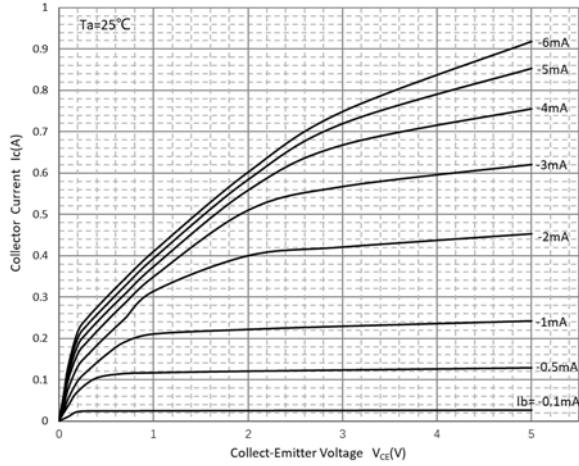


Fig 2: DC Current Gain

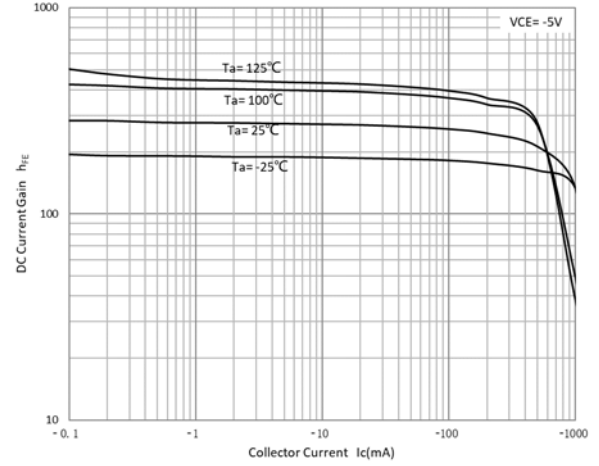


Fig 3: Collector-emitter saturation voltage

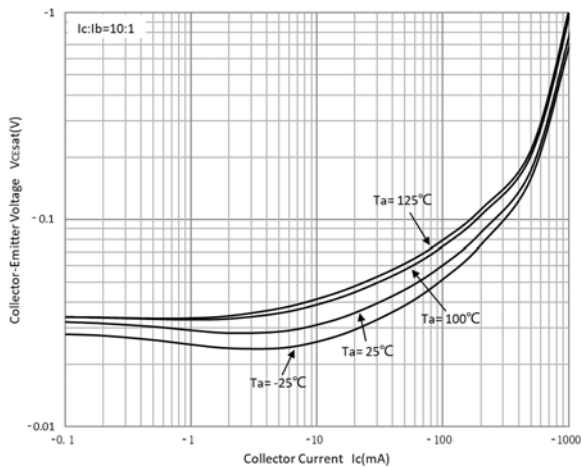


Fig 4: Base-emitter saturation voltage

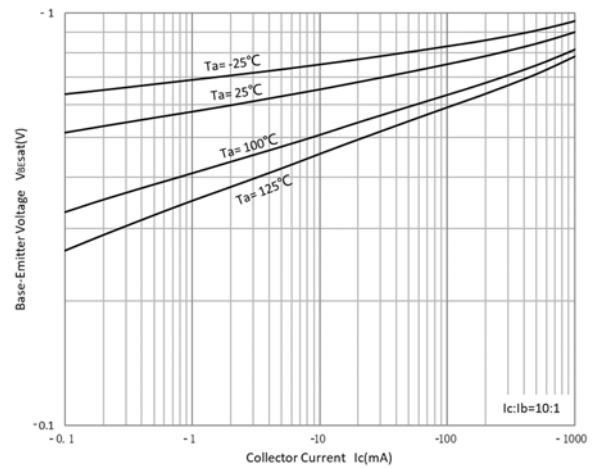


Fig 5: Base-emitter on voltage

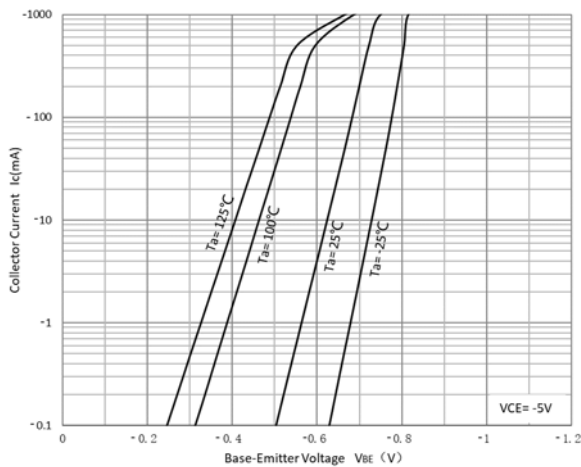


Fig 6: Cob/Cib-Vcb/VEB

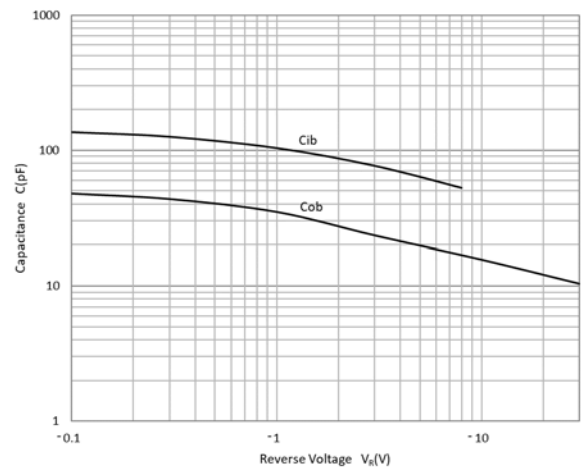
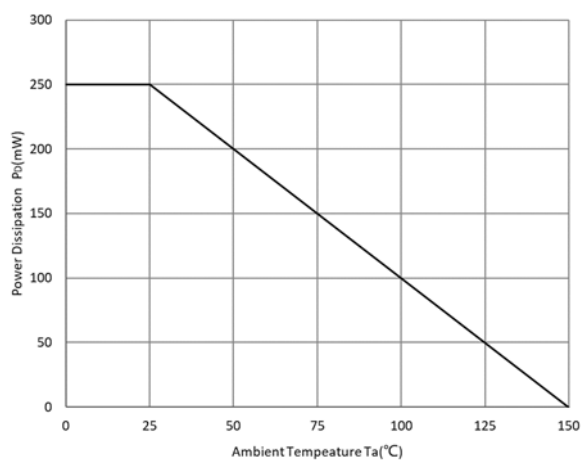
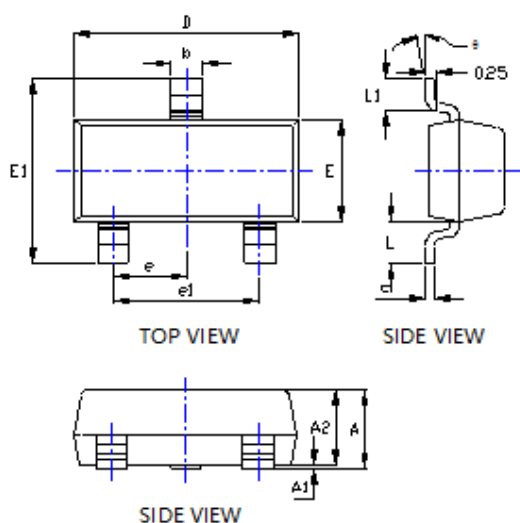


Fig 7: P_D - T_a Curve

■ Ordering Information

Preferred P/N	Packing code	Unit weight(g)	Minimum package(pcs)	Inner box quantity(pcs)	Outer carton quantity(pcs)	Delivery mode
FMMT593	F2	Approximate 0.008	3000	30000	120000	7" reel
FMMT593	F4	Approximate 0.008	10000	/	210000	13" reel

■ Outline Dimensions

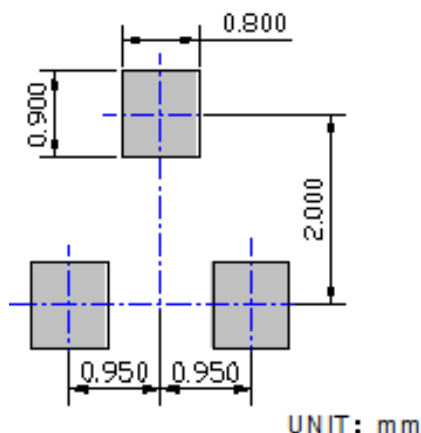


SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
θ	0°	8°	0°	8°

Note:

1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: $\pm 0.10\text{mm}$ unless otherwise specified.
[通用公差为 $\pm 0.10\text{mm}$ ，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
4. All dimensions shown are exclusive of burrs and gate residues. Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5. Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6. Dimensions D and E are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[D和E是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7. Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]

■ Suggested Pad Layout





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